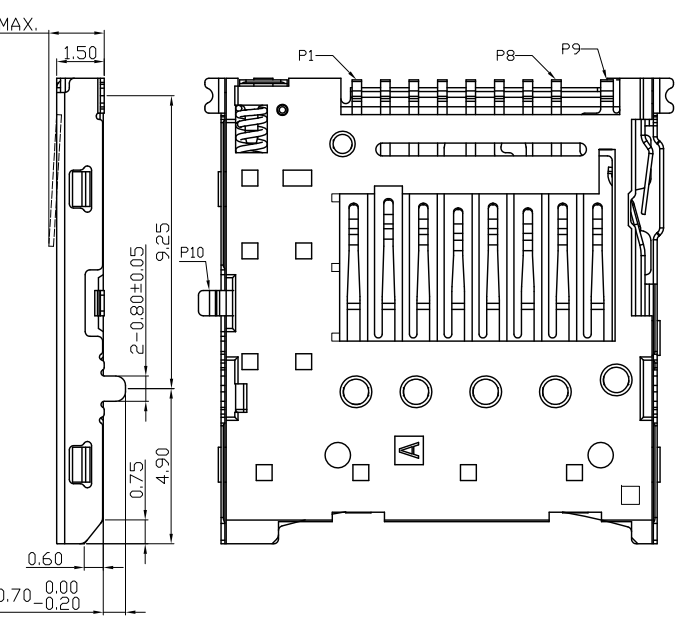
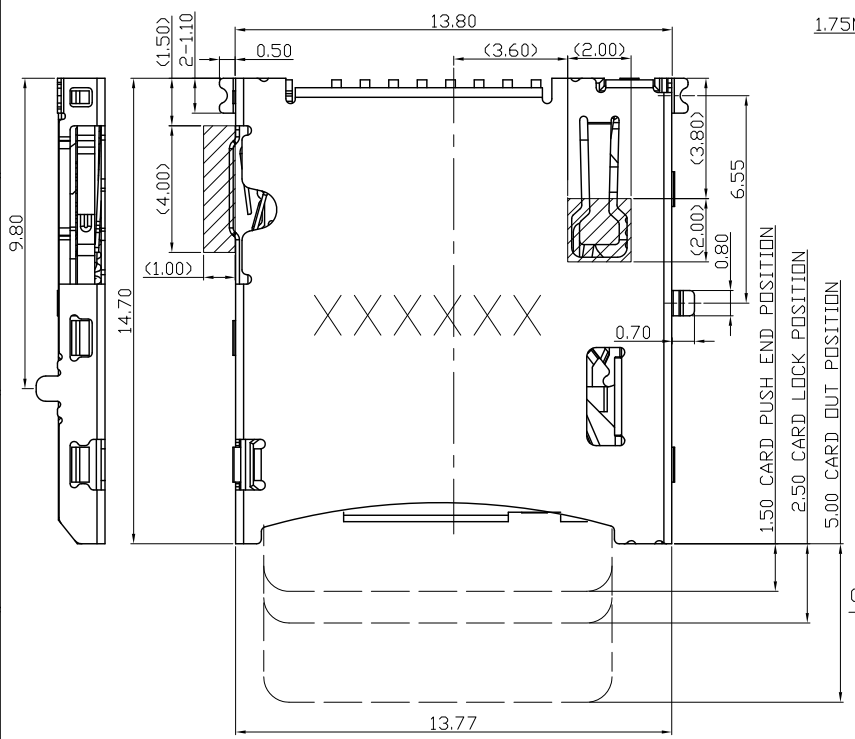
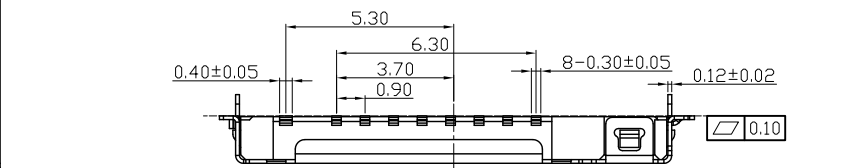


REV.	ECN.NO.	MODIFY.CONTENT

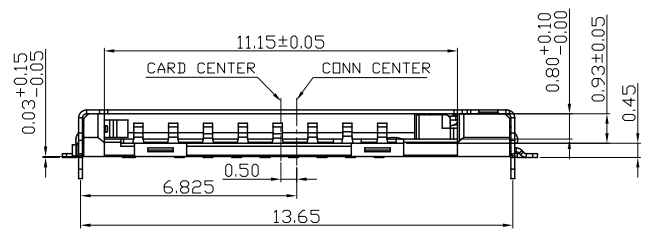
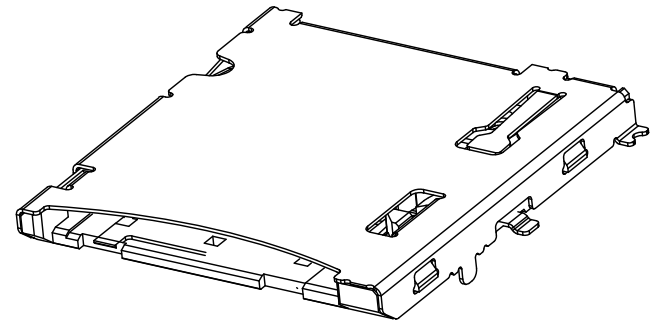


NOTES :

- MATERIAL :
 - HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL SUS304
 - CONTACT: COPPER ALLOY C5210
- FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, GOLD FLASH ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN SOLDERABLE NICKEL PLATING OVERALL. GOLD FLASH ON SOLDERTAIL AREA.
- ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

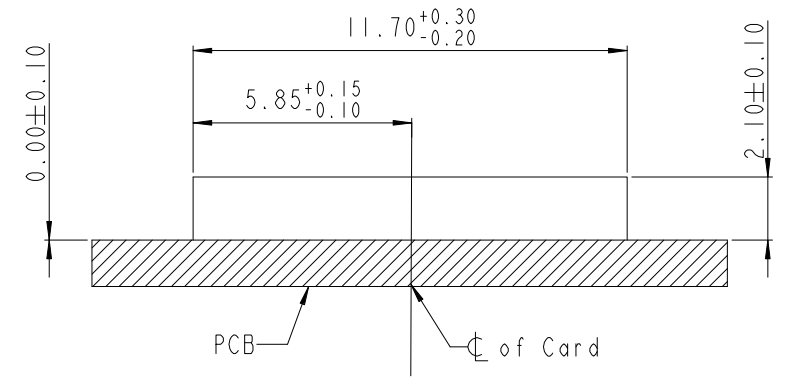
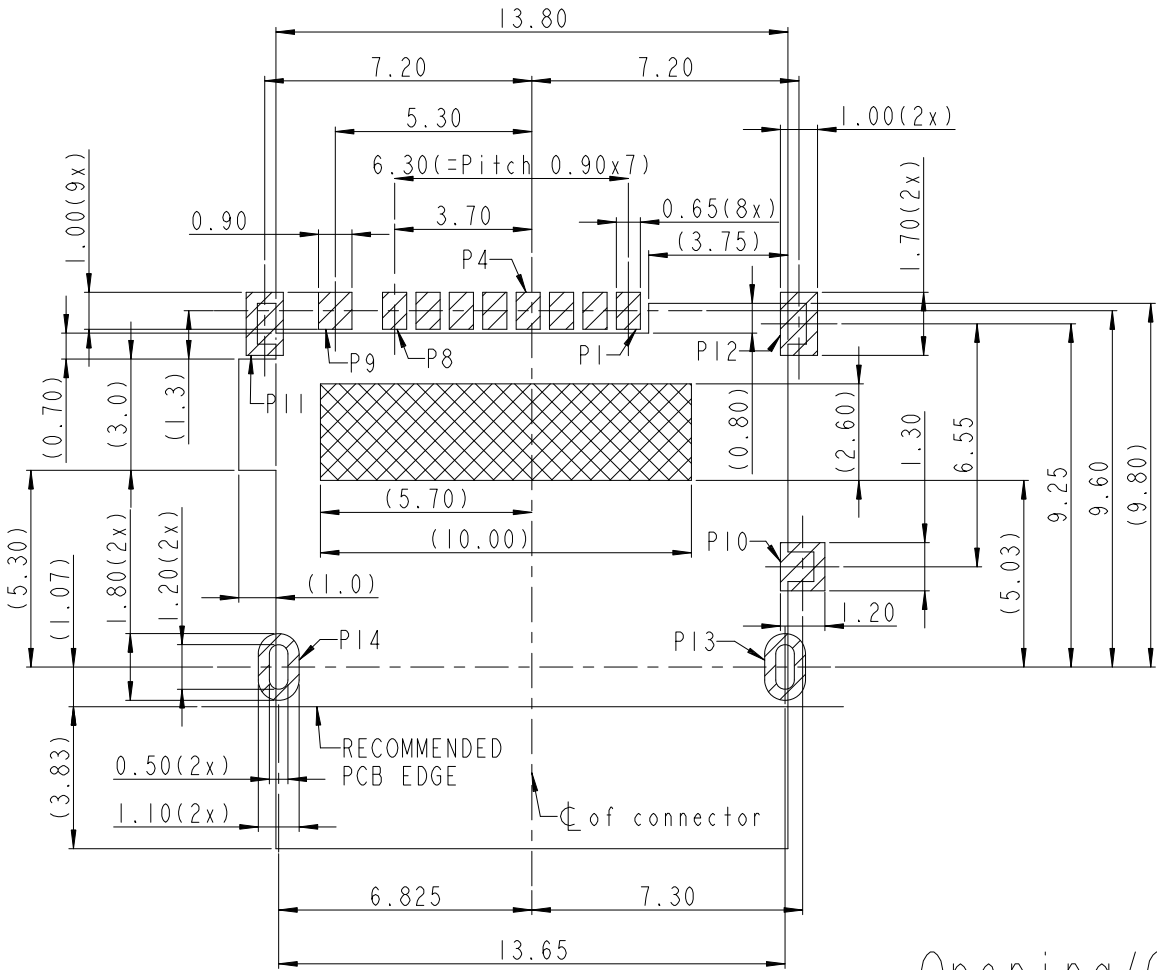
PART.NO.:
MR212-AP401-**

- 08: 功能区镀金1U", 锡脚Gold Flash
- 09: 功能区镀金3U", 锡脚Gold Flash
- 10: 功能区镀金5U", 锡脚Gold Flash
- 11: 功能区镀金15U", 锡脚Gold Flash
- 12: 功能区镀金30U", 锡脚Gold Flash



GENERAL TOLERANCE	DWG.NO.	MR212-AP401-00	PART.NO.	MR212-AP401-**	DRAWN	L.M.J 2020.04.09
x.±0.50	REV.	A	TITLE	Micro SD Push H1.50-2 conn	CHECKED	
.x±0.25	SIZE	A4	SHEET	1 OF 3	APPROVED	
.xx±0.15						

UNIT	mm	SCALE	1:1
 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			



Recommend ID Dimension

PIN ASSIGNMENT

Pin No.	PIN ASSIGNMENT
P1	MICRO SD_DAT2
P2	MICRO SD_CD/DAT3
P3	MICRO SD_CMD
P4	MICRO SD_VDD
P5	MICRO SD_CLK
P6	MICRO SD_VSS
P7	MICRO SD_DAT0
P8	MICRO SD_DAT1
P9	MICRO SD_CD
P10	GND
P11	GND
P12	GND
P13	GND
P14	GND

Opening/Close of Switch

	Card Detect Switch
Card Uninsertion	Open
Card Half Insertion	Open
Card Insertion	Close
N/O	

Recommended P.C.B LAYOUT
TOP VIEW(TOLERANCE+/-0.05)

- : PAD AREA
- : NO COPPER AREA
- : KEEP OUT AREA

GENERAL TOLERANCE	DWG.NO.	MR212-AP401-***
x.±0.50	REV.	A
.x±0.25	SIZE	
.xx±0.15	A4	

PART.NO.	MR212-AP401-***	DRAWN	L.M.J 2020.04.09
TITLE	Micro SD Push H1.50 conn	CHECKED	
SHEET	2 OF 3	APPROVED	

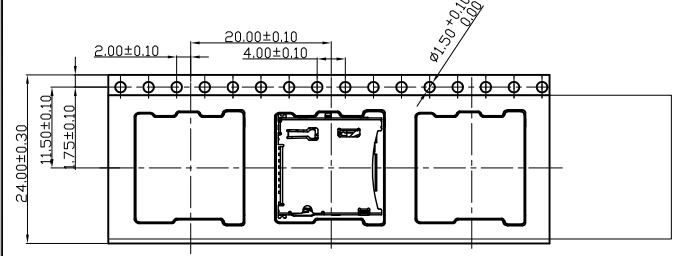
UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			

东莞市欧联电子科技有限公司

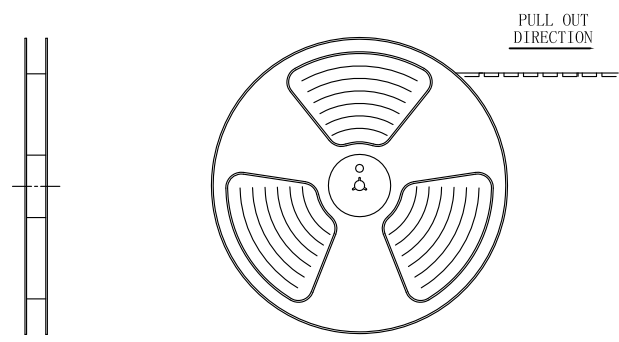
包装作业规范

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

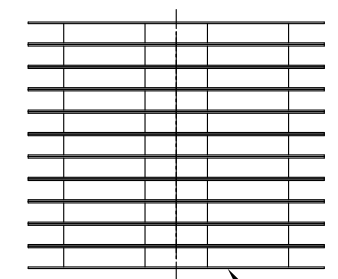
- 一.
- 1) 将成品一一放入REEL包装盘内, 依同一方向放入.
 - 2) 包装时, 如下图所示, 放置 1000 个成品.



- 二.
- 1) 装盘前先把前面空15pcs产品, 然后再开始装盘, 尾端也需空出15pcs产品.
 - 2) 装满成品的REEL包装盘如下图所示.

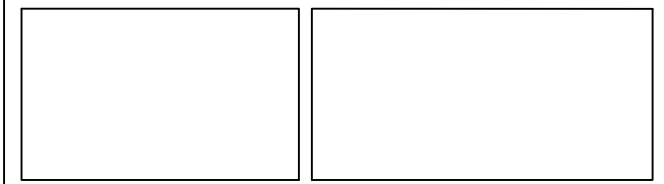


- 三.
- 1) 每箱装 10 盘REEL包装盘.
 - 2) 每箱放置10000PCS 的成品.



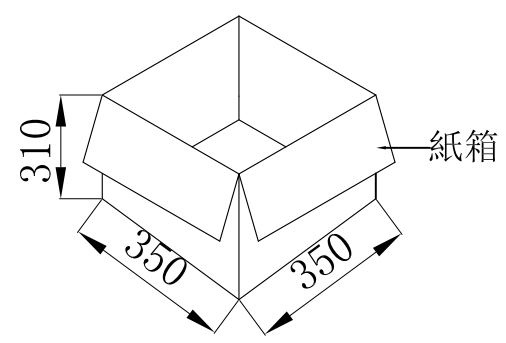
REEL盘

- 四.
- 1) 用TAPE将纸箱封实.



備註 (REMARK)

1. 若有未裝滿之零數箱, 必須以緩衝材塞滿.



GENERAL TOLERANCE		DWG.NO.	MR212-AP401-00	PART.NO.	MR212-AP401-**	DRAWN	L.M.J 2020.04.09
x.±0.50	x.± 5°	REV.	A	TITLE	Micro SD Push H1.50 conn	CHECKED	
.x±0.25	.x± 2°	SIZE		SHEET	3 OF 3	APPROVED	
.xx±0.15	.xx± 1°	A4					

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			